AP30H04NF

40V N+N-Channel Enhancement Mode MOSFET

Description

The AP30H04NF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} = 40V I_D =30A

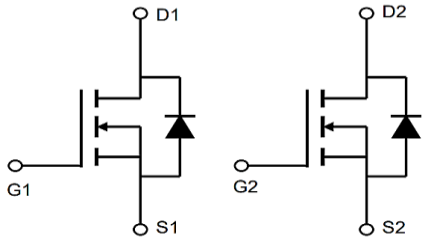
$R_{DS(ON)}$ < 14mΩ @ V_{GS}=10V （**Type：11mΩ**）

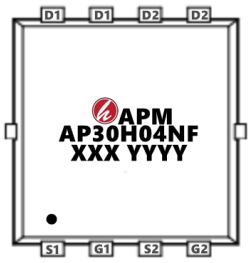
Application

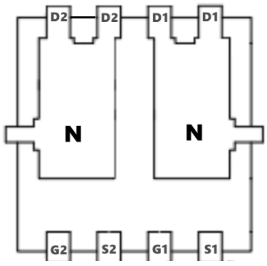
Wireless charging

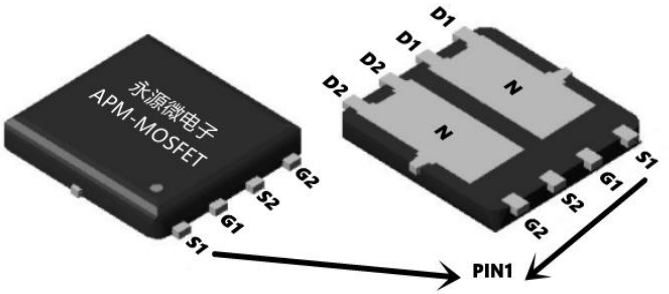
Boost driver

Brushless motor









Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP30H04NF	PDFN5*6-8L	AP30H04NF XXX YYYY	5000

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	40	V
VGS	Gate-Source Voltage	±20	V
I_D@T_A=25℃	Continuous Drain Current[1]	30	A
I_D@T_A=70℃	Continuous Drain Current[1]	21	A
IDM	Pulsed Drain Current[2]	36	A
EAS	Single Pulse Avalanche Energy[3]	31	mJ
IAS	Avalanche Current	25	A
P_D@T_A=25℃	Total Power Dissipation[4]	1.9	W
TSTG	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃
$R_{\theta JA}$	Thermal Resistance Junction-ambient[1](t≤10s)	25	℃/W
$R_{\theta JC}$	Thermal Resistance Junction-ambient[1]	8	℃/W

Electrical Characteristics (T_C=25℃unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	40	44	---	V
△BVDSS/△TJ	BVDSS Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	0.034	---	V/℃
RDS(ON)	Static Drain-Source On-Resistance[2]	V_{GS}=10V , I_D=8A	---	11	14	mΩ
		V_{GS}=4.5V , I_D=6A	---	13	18	
VGS(th)	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1.0	1.6	2.5	V
△$V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5.64	---	mV/℃
IDSS	Drain-Source Leakage Current	V_{DS}=32V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=32V , V_{GS}=0V , T_J=55℃	---	---	5	
IGSS	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
gfs	Forward Transconductance	V_{DS}=5V , I_D=8A	---	36	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	2.1	---	Ω
Q_g	Total Gate Charge (4.5V)	V_{DS}=20V , V_{GS}=4.5V , I_D=8A	---	10.7	---	nC
Qgs	Gate-Source Charge		---	3.3	---	nC
Qgd	Gate-Drain Charge		---	4.2	---	nC
Td(on)	Turn-On Delay Time	V_{DD}=12V V_{GS}=10V R_G=3.3Ω I_D=6A	---	8.6	---	ns
T_r	Rise Time		---	3.4	---	ns
Td(off)	Turn-Off Delay Time		---	24.8	---	ns
T_f	Fall Time		---	2.2	---	ns
Ciss	Input Capacitance	V_{DS}=15V , V_{GS}=0V , f=1MHz	---	1314	---	pF
Coss	Output Capacitance		---	120	---	
Crss	Reverse Transfer Capacitance		---	88	---	
IS	Continuous Source Current[1,5]	V_G=V_D=0V , Force Current	---	---	8.5	A
ISM	Pulsed Source Current[2,5]		---	---	34	A
VSD	Diode Forward Voltage[2]	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1.2	V

Note :

1、The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper.

2、The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%

3、EAS condition: TJ=25℃, VDD=32V,VGS=10V,L=0.1Mh,IAS=22A

4、The power dissipation is limited by 150℃ junction temperature

5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

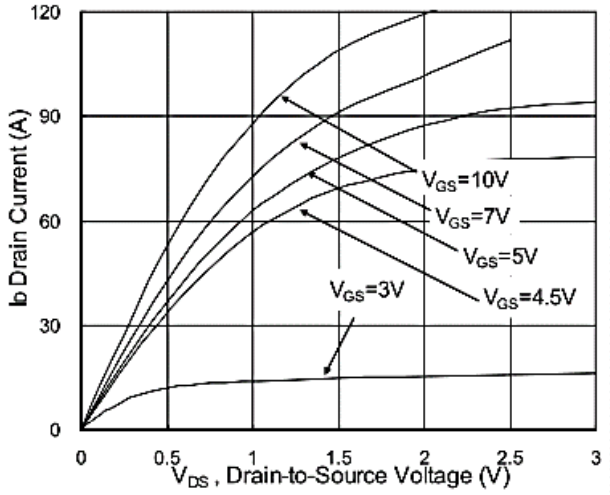


Fig.1 Typical Output Characteristics

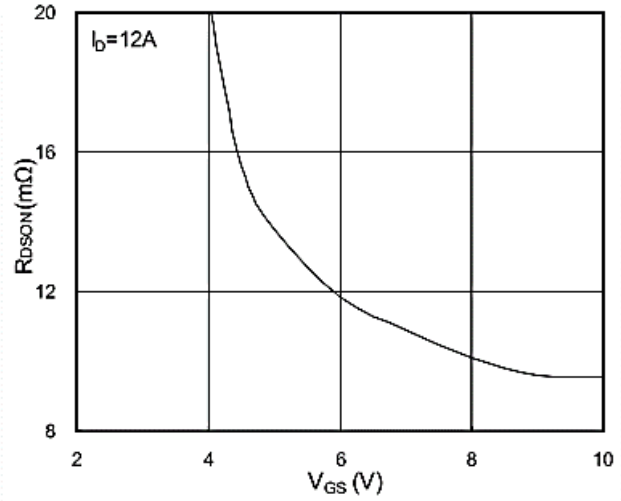


Fig.2 On-Resistance vs. G-S Voltage

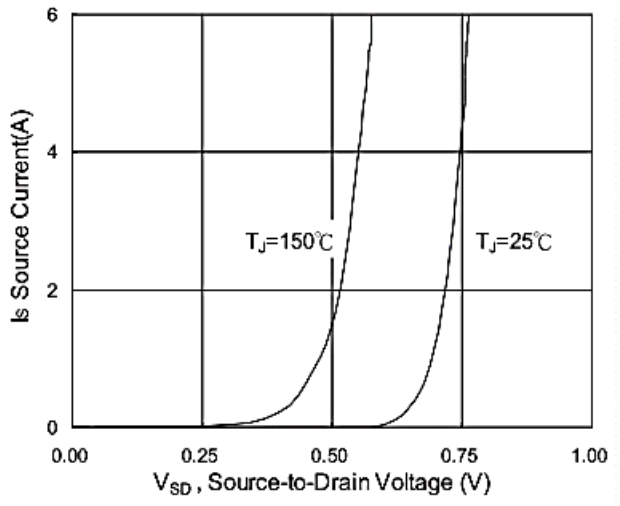


Fig.3 Forward Characteristics of Reverse

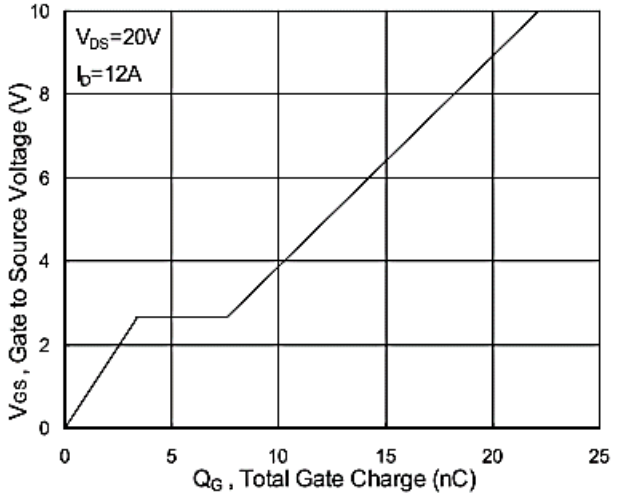


Fig.4 Gate-Charge Characteristics

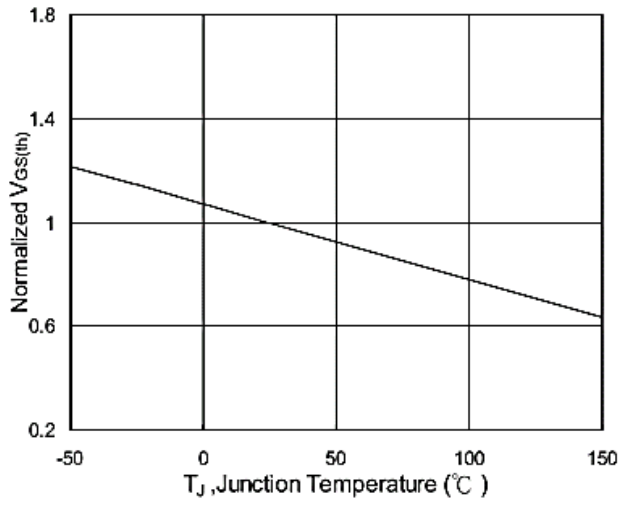


Fig.5 $V_{GS(th)}$ vs. T_J

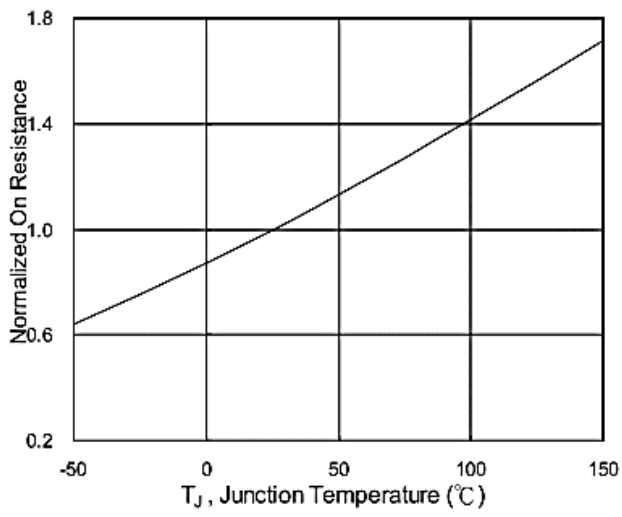


Fig.6 Normalized R_{DSON} vs. T_J

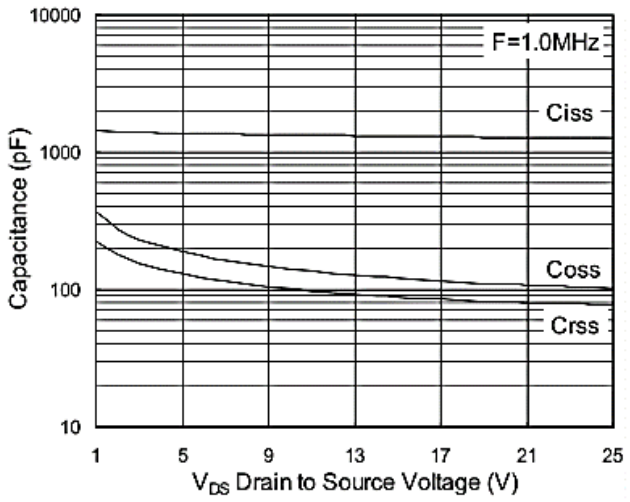


Fig.7 Capacitance

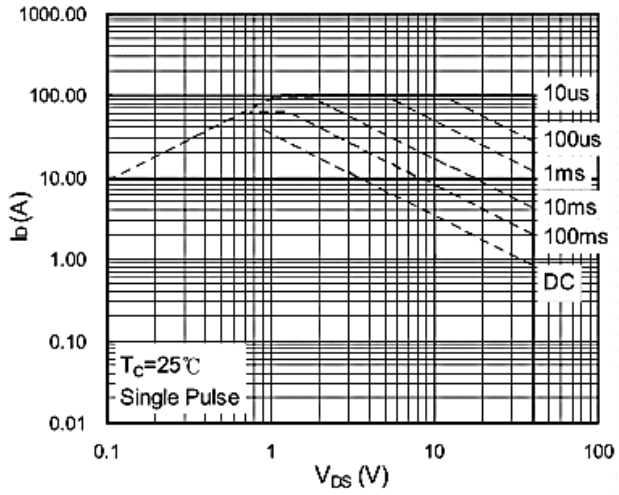


Fig.8 Safe Operating Area

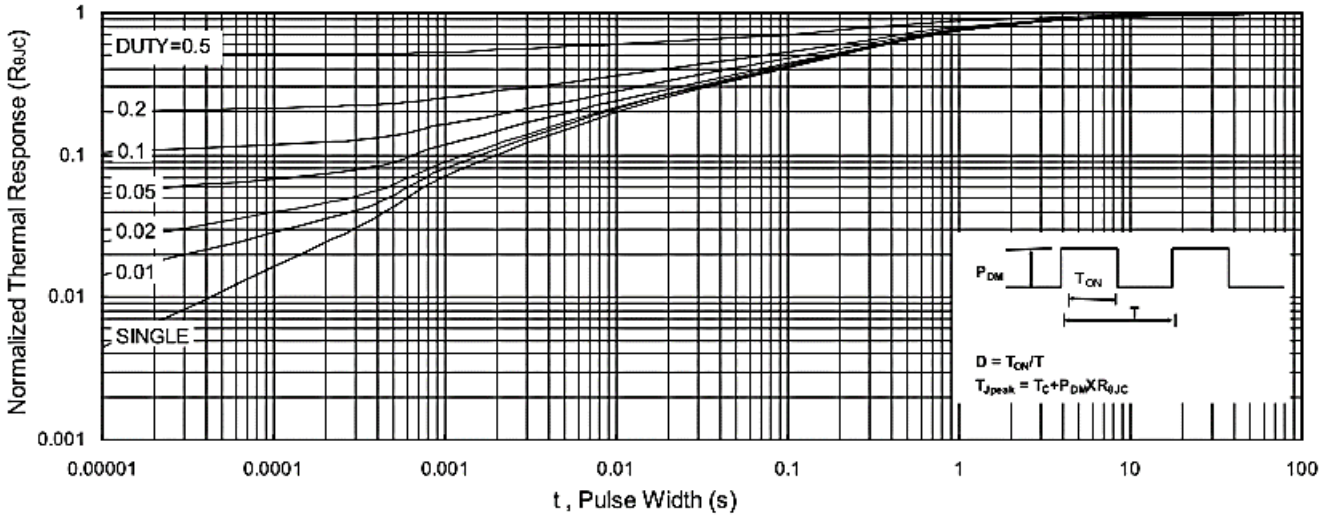


Fig.9 Normalized Maximum Transient Thermal Impedance

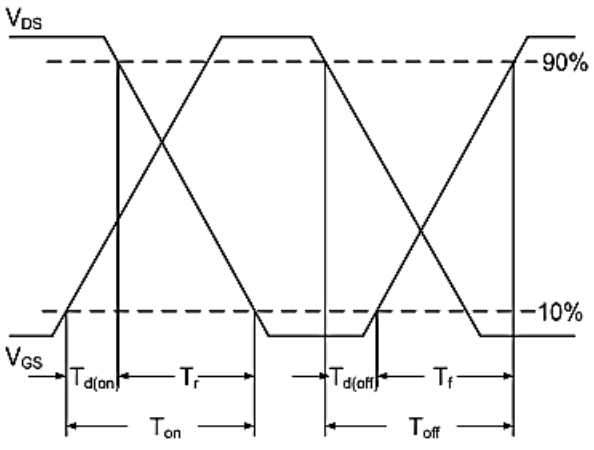


Fig.10 Switching Time Waveform

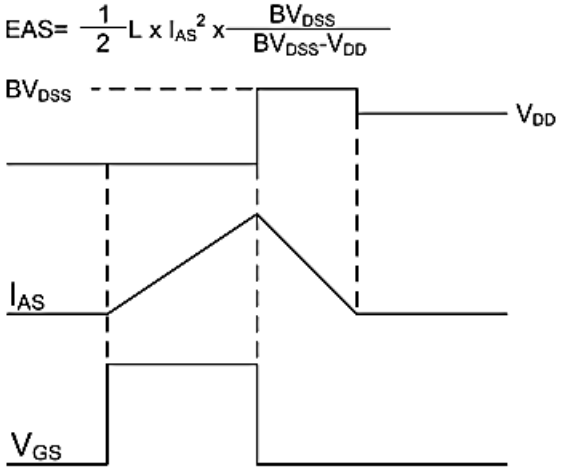
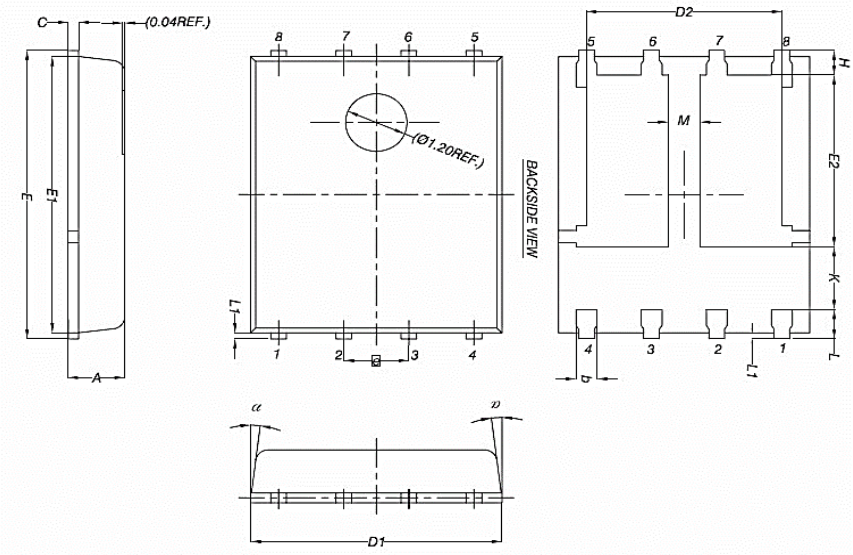


Fig.11 Unclamped Inductive Switching Waveform

Package Mechanical Data-DFN5*6-8L-JQ Double



Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.90	1.00	1.10
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	3.30	3.45
E2	3.38	3.05	3.20
e		1.27BSC	
H	0.41	0.51	0.61
K	1.10	--	--
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
M	0.50	--	--
a	0°	--	12°

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40V N+N-Channel Enhancement Mode MOSFET

Edition	Date	Change
Rve1.0	2022/1/23	Initial release